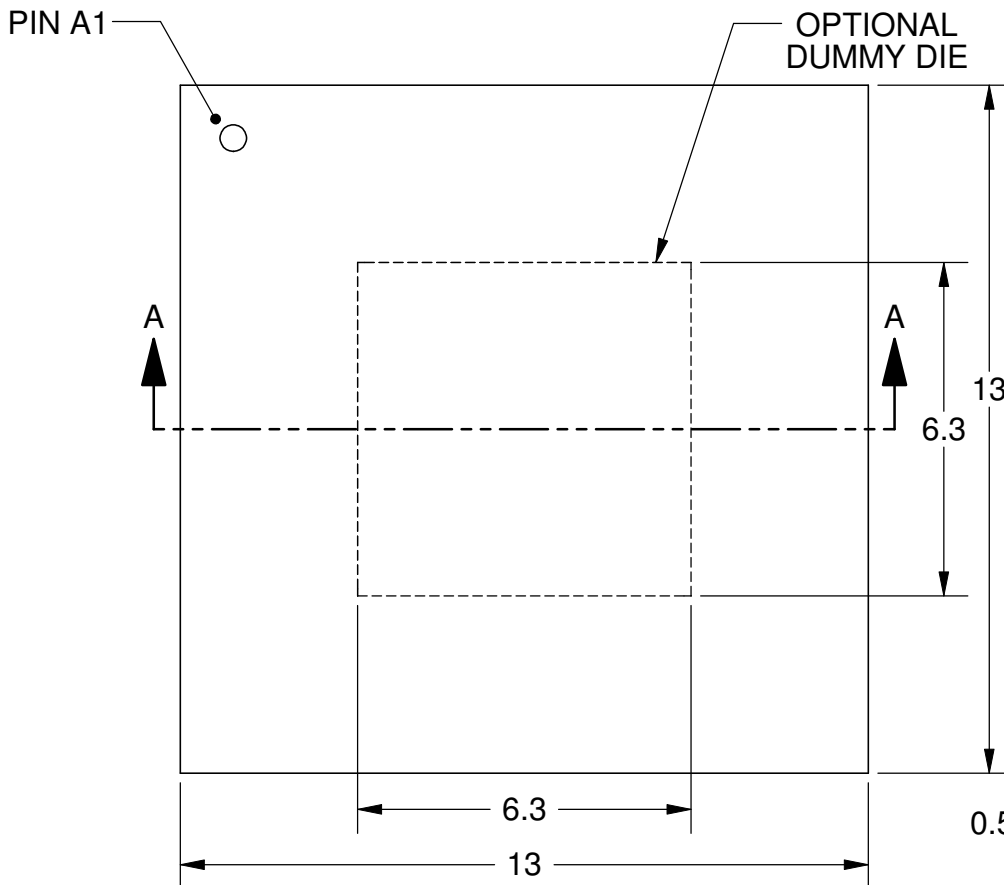
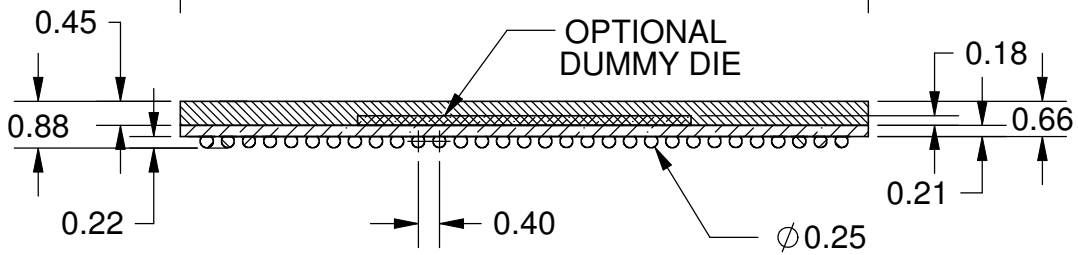
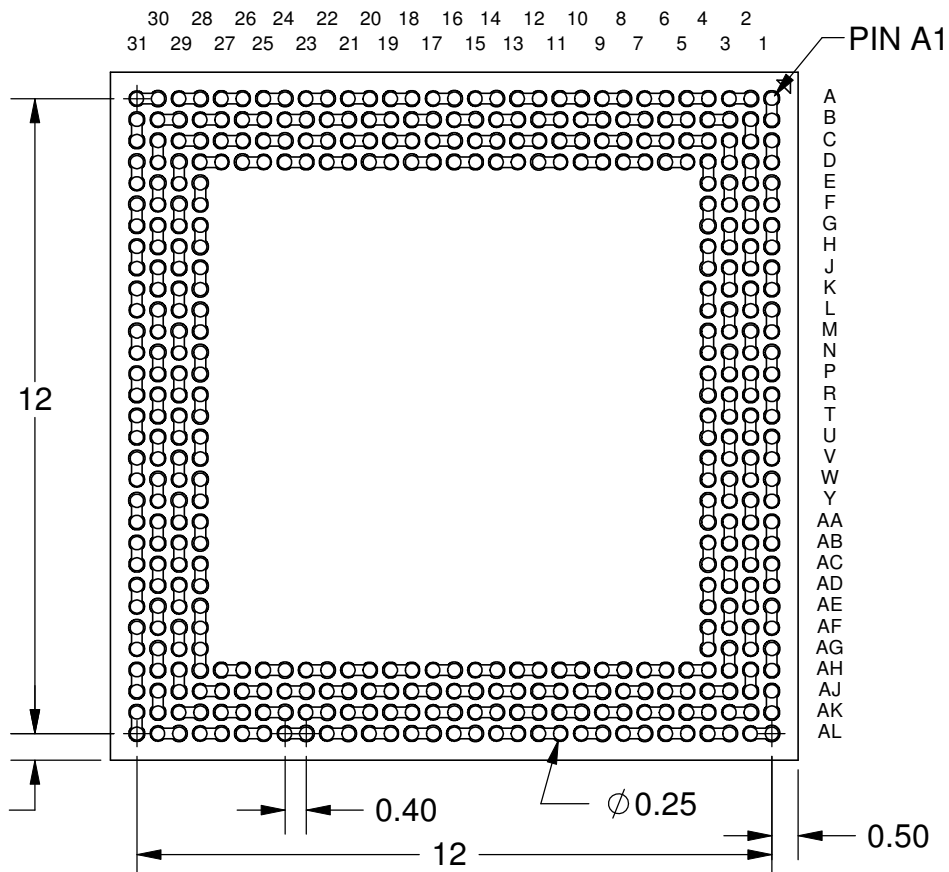


TOP VIEW



BALL VIEW




SECTION A-A

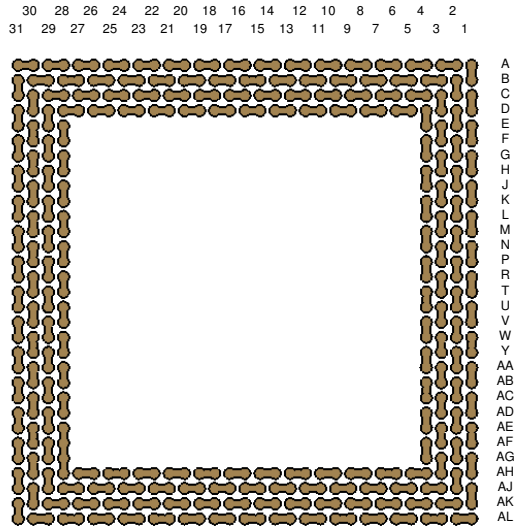
Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.25mm.
- 4) SOLDER MASK DEFINED PAD OPENING: 0.20mm.
- 5) PAD Cu DIAMETER: 0.30mm.
- 6) SUBSTRATE MATERIAL: BT.
- 7) DUMMY DIE IS OPTIONAL.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMEND BAKING 24 HOURS @ 125C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

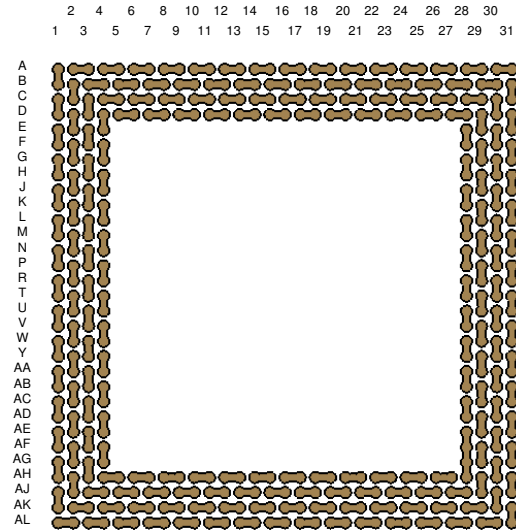
PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
BGA432T.4C-DC313	Sn96.5/Ag3.0/Cu0.5	YES	YES	NO
BGA432T.4C-DC313D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
BGA432T.4-DC313	Sn63/Pb37	NO	NO	NO
BGA432T.4-DC313D	Sn63/Pb37	NO	NO	YES

TOLERANCE UNLESS NOTED		APPROVALS		DATE				
X.X	+/- 0.10	DRAWN J. Hines		7/16/2011				
X.XX	+/- 0.05	ENG			TITLE BGA432T.4C-DC313D			
X.XXX	+/- 0.025	MFG			DAISY CHAIN DUMMY			
ANGLES +/- 0.5°		QA			SCALE 7:1	SIZE A	DRAWING NO. 543133	REV A
ALL DIMENSIONS IN INCHES <input type="checkbox"/> MILLIMETERS <input checked="" type="checkbox"/>		CUST			DO NOT SCALE DRAWING			
THIRD ANGLE PROJECTION		REVISED			SHEET 1 OF 2			

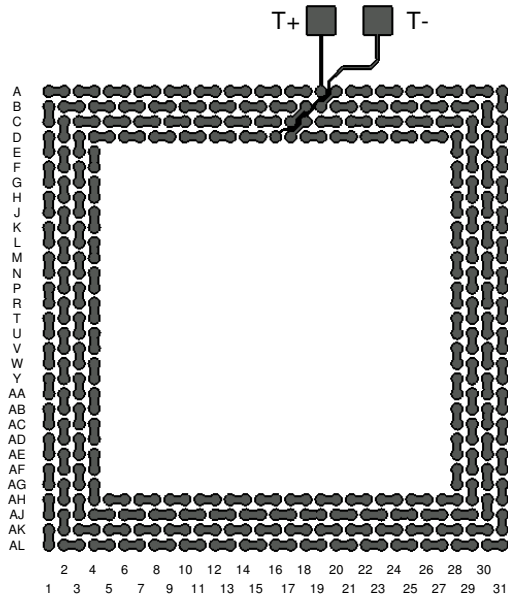
BALL VIEW



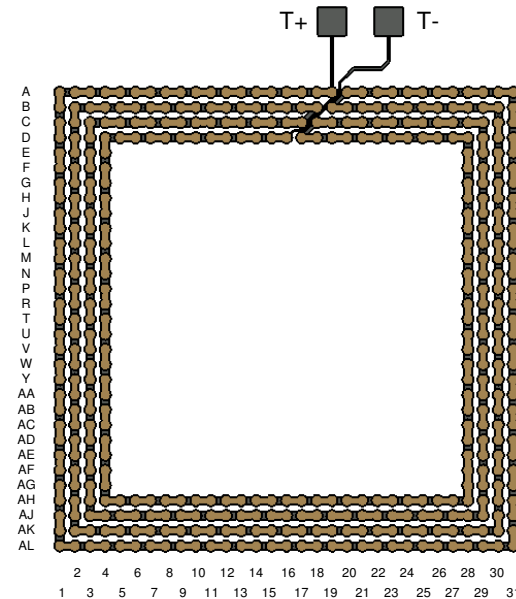
BOTTOM SIDE
(TOP X-RAY VIEW)



TOP VIEW



AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)



TEST VEHICLE BOARD

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.30mm (11.8mil).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.20mm (7.8mil).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.20mm (7.8mil).

TopLine ®			
TITLE		BGA432T.4C-DC313D DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
5:1	A	543133	A
DO NOT SCALE DRAWING			SHEET 2 OF 2